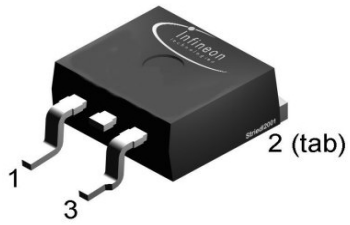
MOSFET

OptiMOS™ 5 Linear FET, 100 V

D²PAK



Features

- Ideal for hot-swap and e-fuse applications
- Very low on-resistance $R_{DS(on)}$
- Wide safe operating area SOA
- N-channel, normal level
- 100% avalanche tested
- Pb-free plating; RoHS compliant
- Qualified according to JEDEC[1] for target applications
- Halogen-free according to IEC61249-2-21

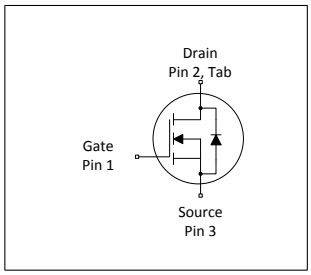


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	2.0	mΩ
I_D (silicon limited)	289	A
I_D (package limited)	120	A
I_{pulse} (V_{DS}=56 V, t_p=10 ms)	10.2	A

Type / Ordering Code	Package	Marking	Related Links
IPB020N10N5LF	PG-TO 263-3	020N10LF	-

[1] J-STD20 and JESD22

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1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current	I_D	- - -	- - -	120 120 29	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10 V, T_C=25 °C, R_{thJA} =40 K/W[1)]
Pulsed drain current[2)]	$I_{D,pulse}$	-	-	480	A	T_C=25 °C
Avalanche energy, single pulse[3)]	E_{AS}	-	-	979	mJ	I_D=100 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	313	W	T_C=25 °C
Operating and storage temperature	T_j, T_{stg}	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	0.25	0.4	K/W	-
Device on PCB, minimal footprint	R_{thJA}	-	-	62	K/W	-
Device on PCB, 6 cm² cooling area[1)]	R_{thJA}	-	-	40	K/W	-

[1)] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[2)] See Diagram 3 for more detailed information
[3)] See Diagram 13 for more detailed information

3 Electrical characteristics

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.5	3.3	4.1	V	V_{DS}=V_{GS}, I_D=270 µA
Zero gate voltage drain current	I_{DSS}	- -	1 10	10 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	- -	2 -2	5 -5	µA	V_{GS}=20 V, V_{DS}=0 V V_{GS}=-10 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	1.8	2	mΩ	V_{GS}=10 V, I_D=100 A
Gate resistance[1)]	R_G	-	44	66	Ω	-
Transconductance	g_{fs}	31	62	-	S	|V_{DS}|>2|I_D|$R_{DS(on)max}$, I_D=100 A

Table 5 Dynamic characteristics[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	650	840	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance	C_{oss}	-	1900	2500	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Reverse transfer capacitance	C_{rss}	-	25	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	7	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.7 Ω
Rise time	t_r	-	28	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.7 Ω
Turn-off delay time	$t_{d(off)}$	-	128	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.7 Ω
Fall time	t_f	-	82	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.7 Ω

Table 6 Gate charge characteristics[2)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	4.4	-	nC	V_{DD}=50 V, I_D=180 A, V_{GS}=0 to 10 V
Gate to drain charge[1)]	Q_{gd}	-	141	-	nC	V_{DD}=50 V, I_D=180 A, V_{GS}=0 to 10 V
Gate charge total[1)]	Q_g	-	195	-	nC	V_{DD}=50 V, I_D=180 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	7.1	-	V	V_{DD}=50 V, I_D=180 A, V_{GS}=0 to 10 V
Output charge[1)]	Q_{oss}	-	209	-	nC	V_{DD}=50 V, V_{GS}=0 V

[1)] Defined by design. Not subject to production test.
[2)] See ″Gate charge waveforms″ for parameter definition

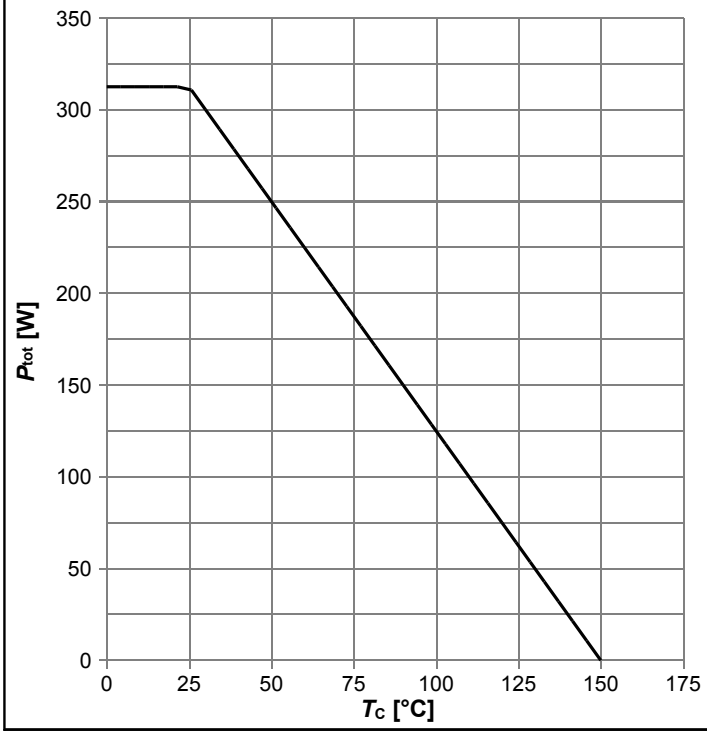
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	120	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	480	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.89	1.2	V	V_{GS}=0 V, I_F=100 A, T_j=25 °C
Reverse recovery time[1)]	t_{rr}	-	62	-	ns	V_R=50 V, I_F=50A, di_F/dt=100 A/µs
Reverse recovery charge[1)]	Q_{rr}	-	113	-	nC	V_R=50 V, I_F=50A, di_F/dt=100 A/µs

[1)] Defined by design. Not subject to production test.

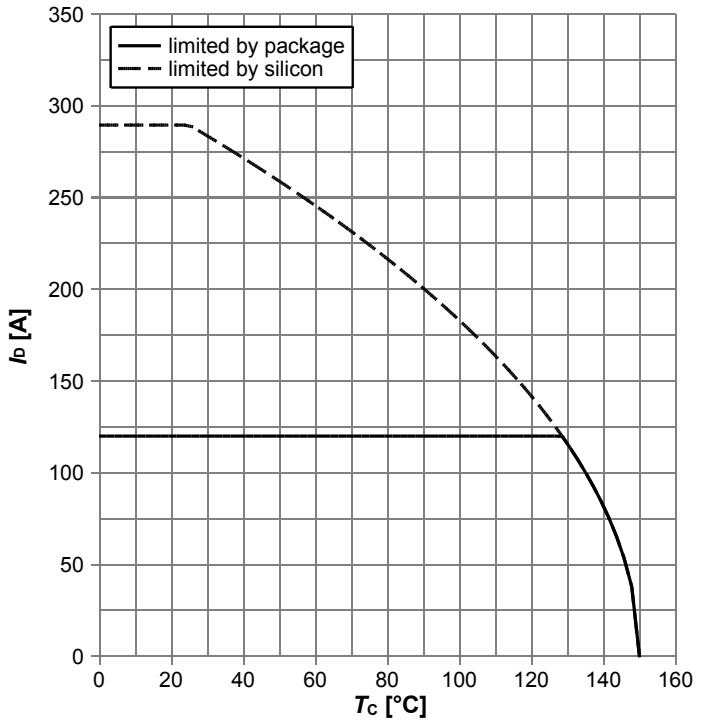
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



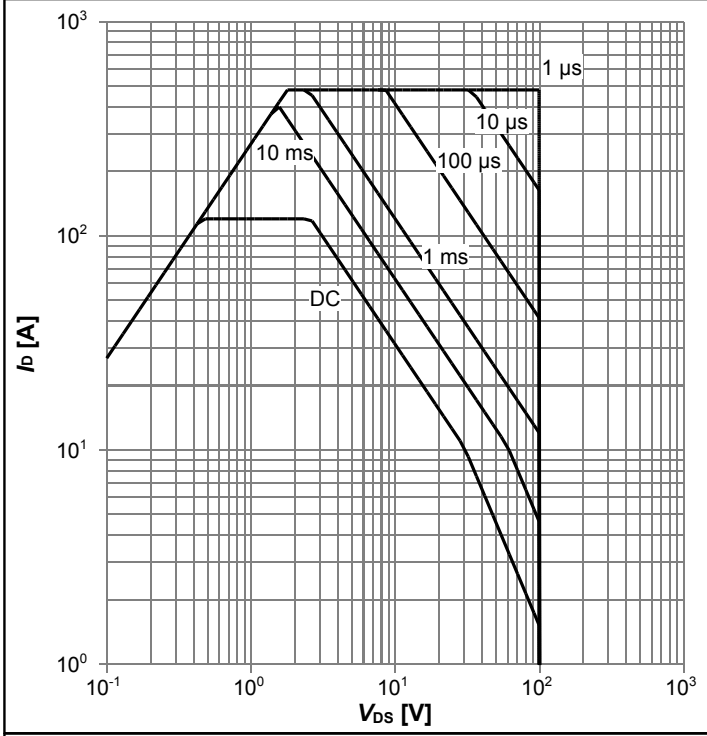
$P_{tot}=f(T_C)$

Diagram 2: Drain current



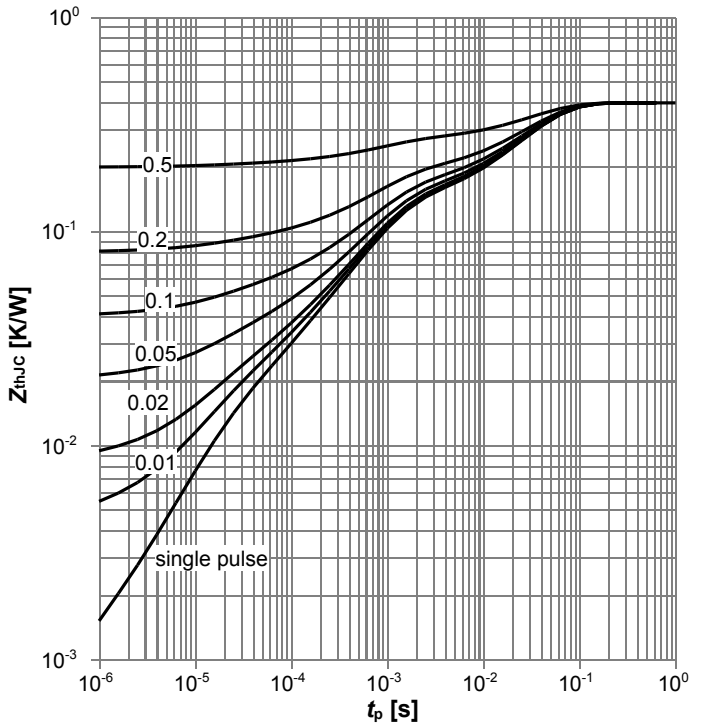
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



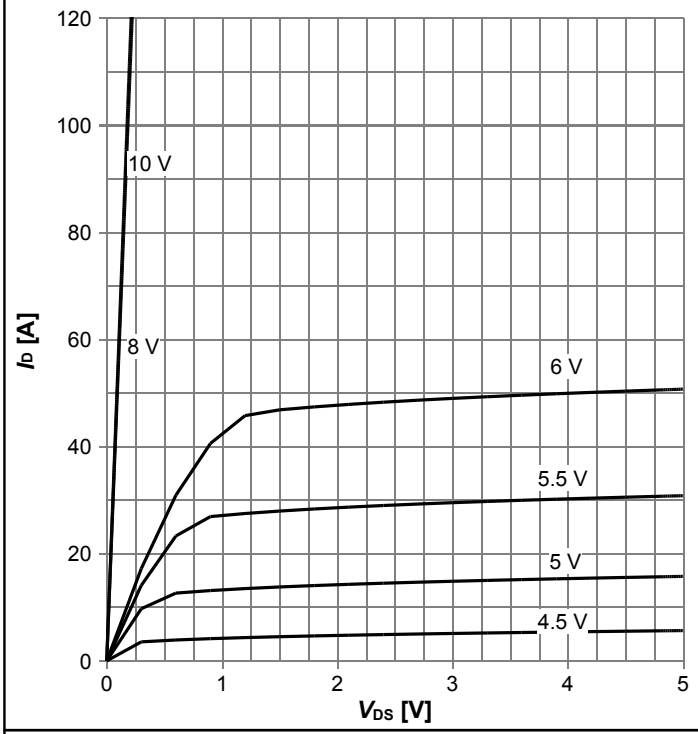
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Max. transient thermal impedance



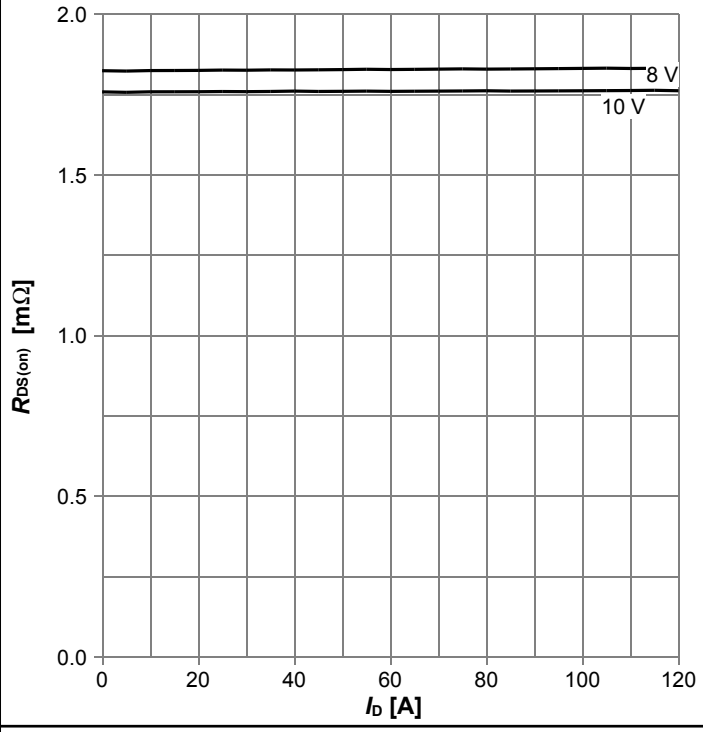
$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



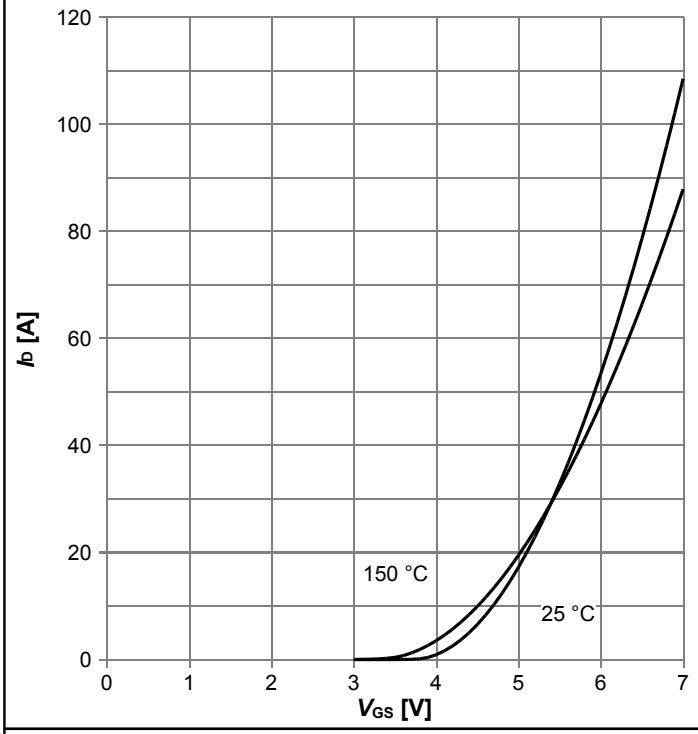
I_D=f(V_{DS}); T_j=25 °C, t_p=30 µs; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



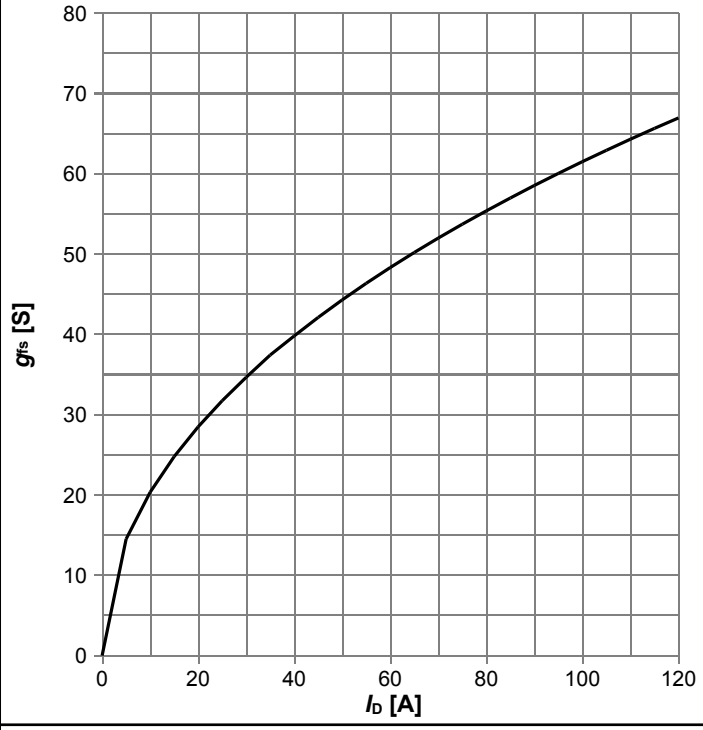
$R_{DS(on)}$=f(I_D); T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



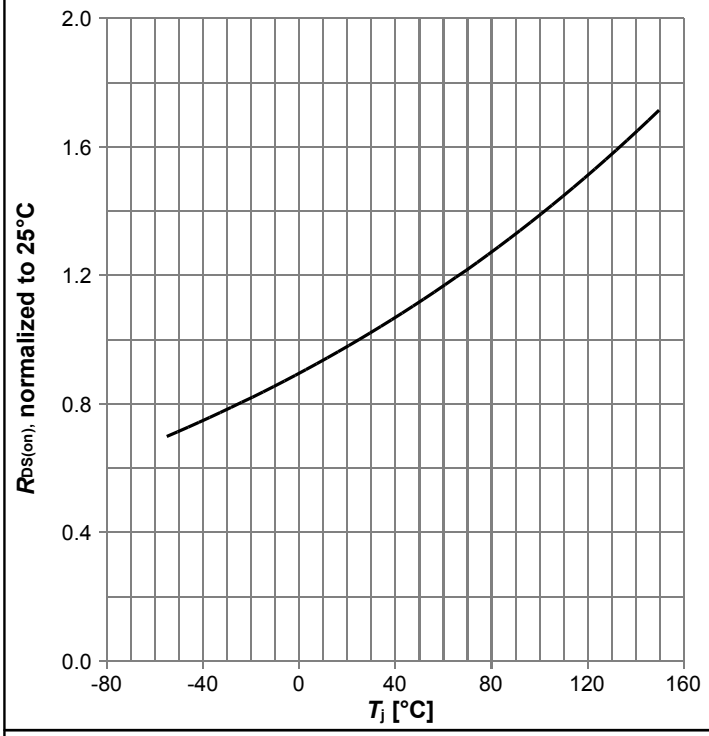
I_D=f(V_{GS}); V_{DS}=10 V; parameter: T_j

Diagram 8: Typ. forward transconductance



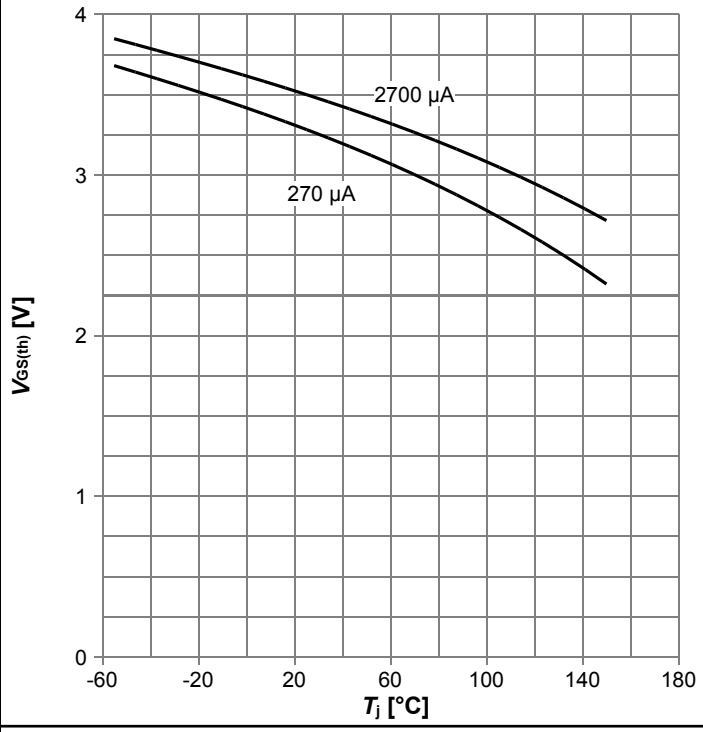
g_{fs}=f(I_D); T_j=25 °C

Diagram 9: Normalized drain-source on-state resistance



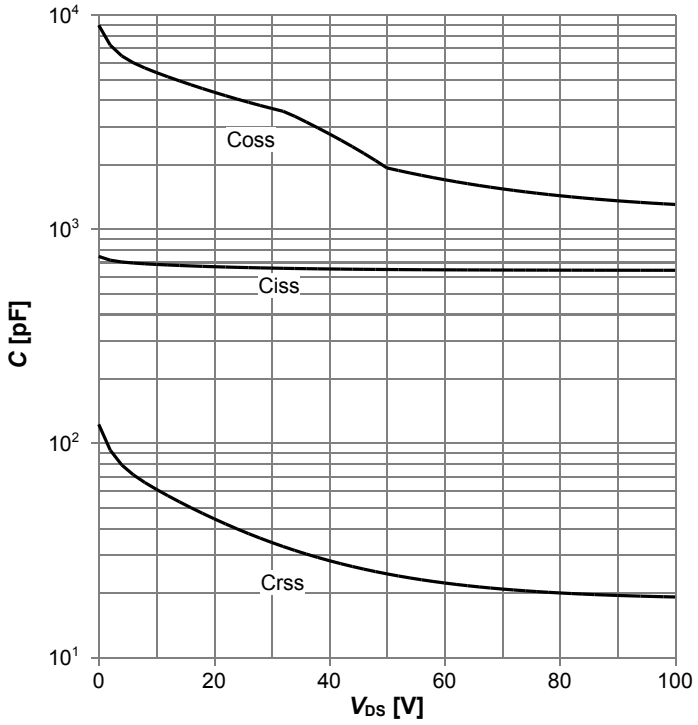
$R_{DS(on)}=f(T_j)$, I_D=100 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



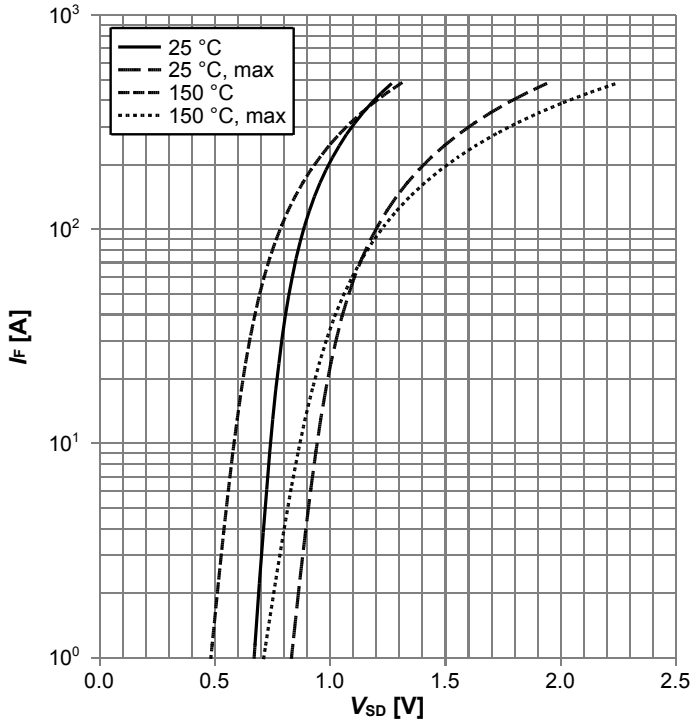
$V_{GS(th)}=f(T_j)$; $V_{GS}=V_{DS}$

Diagram 11: Typ. capacitances



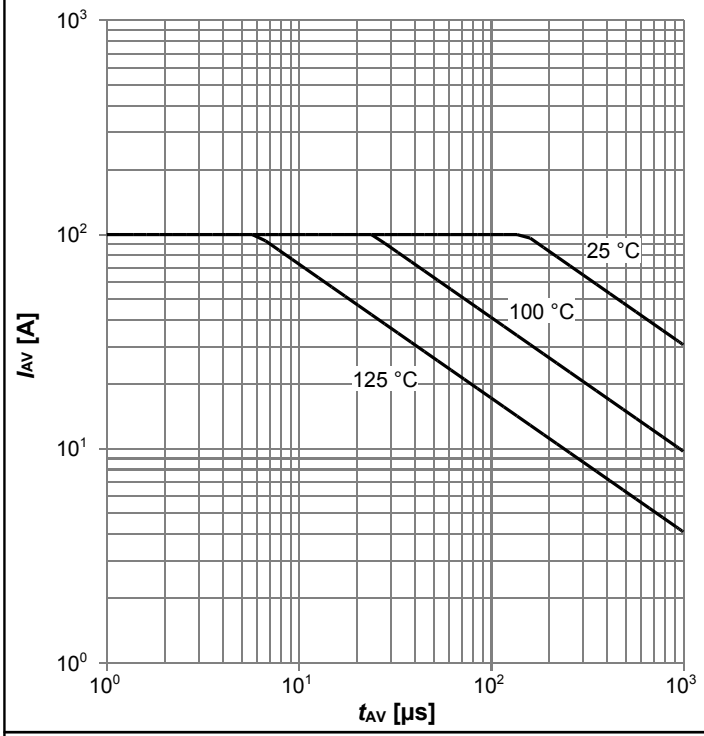
$C=f(V_{DS})$; V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



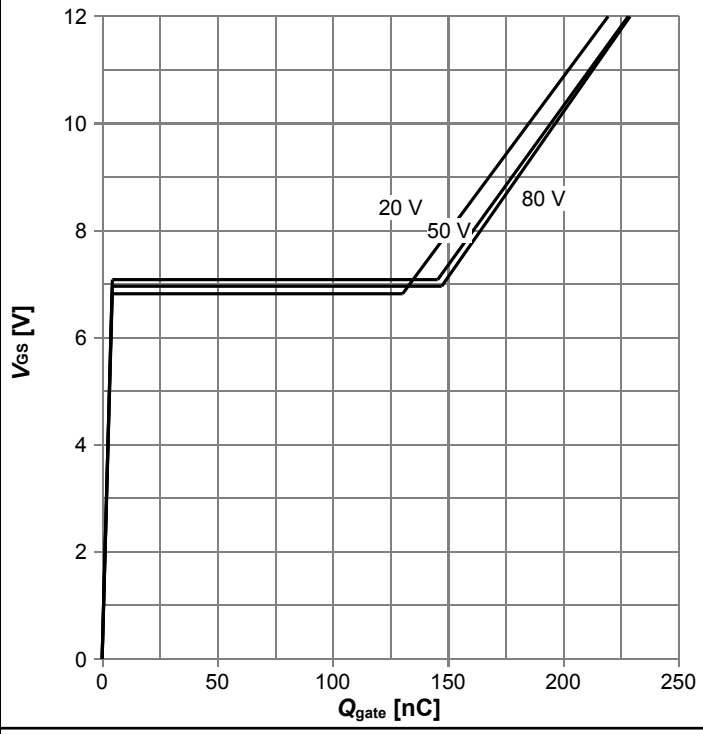
$I_F=f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



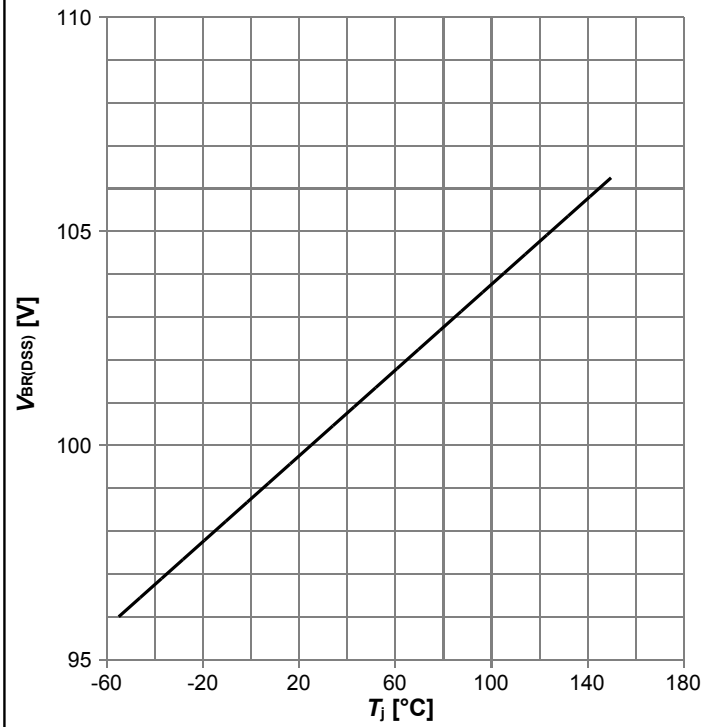
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j(start)}$

Diagram 14: Typ. gate charge



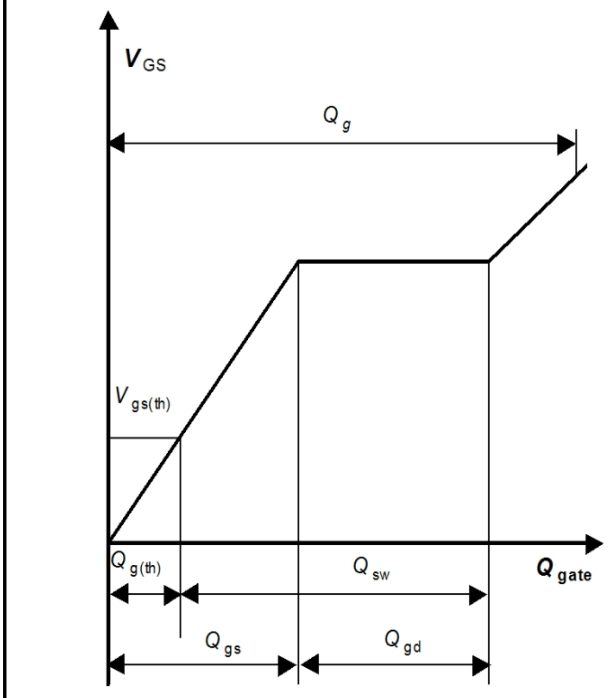
V_{GS}=f(Q_{gate}); I_D=100 A pulsed, resistive load; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

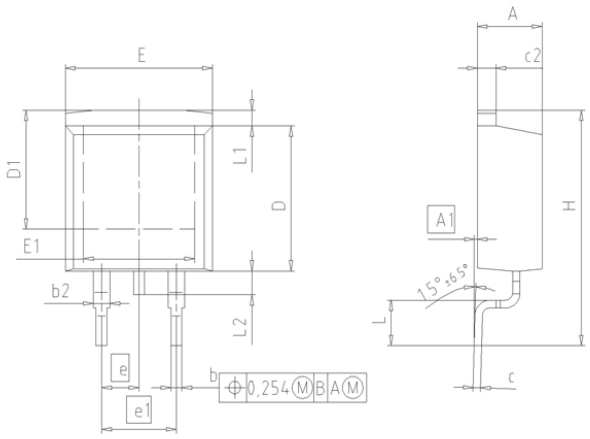


$V_{BR(DSS)}$=f(T_j); I_D=1 mA

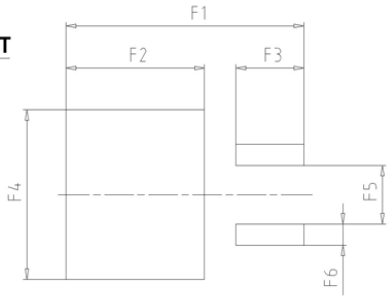
Gate charge waveforms



5 Package Outlines



FOOTPRINT



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	0.00	0.25	0.000	0.010
b	0.65	0.85	0.026	0.033
b2	0.95	1.15	0.037	0.045
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.51	9.45	0.335	0.372
D1	7.10	7.90	0.280	0.311
E	9.80	10.31	0.386	0.406
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	2		2	
H	14.61	15.88	0.575	0.625
L	2.29	3.00	0.090	0.118
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
F1	16.05	16.25	0.632	0.640
F2	9.30	9.50	0.366	0.374
F3	4.50	4.70	0.177	0.185
F4	10.70	10.90	0.421	0.429
F5	3.65	3.85	0.144	0.152
F6	1.25	1.45	0.049	0.057

DOCUMENT NO.
Z8B00003324

SCALE
0 5 5
7.5mm

EUROPEAN PROJECTION

ISSUE DATE
30-08-2007

REVISION
01

Figure 1 Outline PG-TO 263-3, dimensions in mm/inches

Revision History

IPB020N10N5LF

Revision: 2017-02-16, Rev. 2.1

Previous Revision		
Revision	Date	Subjects (major changes since last revision)
2.0	2016-12-15	Release of final version
2.1	2017-02-16	Update technology heading

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